



LMV55x 3MHz、Micropower RROアンプ

1 特長

- 3Vおよび5Vでの性能を規定
- 高いユニティ・ゲイン帯域幅: 3MHz
- 消費電流(アンプごと): 37 μ A
- CMRR: 93dB
- PSRR: 90dB
- スルーレート: 1V/ μ s
- 100k Ω 負荷における出力スイング: レールから70mV
- 全高調波歪み: 1kHz、2k Ω において0.003%
- 温度範囲: -40 $^{\circ}$ C $\sim$ 125 $^{\circ}$ C

2 アプリケーション

- アクティブ・フィルタ
- 携帯機器
- 車載用機器
- バッテリ電源システム
- センサおよび計測機器

3 概要

LMV55xは高性能、低消費電力のオペアンプで、TIの先進のVIP50プロセスにより実装されています。3MHzの帯域幅を持ちながら、アンプごとに37 μ Aの電流しか消費せず、このクラスのオペアンプとしては極めて優れた帯域幅/電力比を実現しています。これらの超低消費電力アンプはユニティ・ゲイン安定で、広い帯域幅を必要とする超低消費電力アプリケーション向けの非常に優れたソリューションです。

LMV55xにはレール・ツー・レール出力段があり、同相入力範囲がグラウンドより低い電圧まで拡張されています。

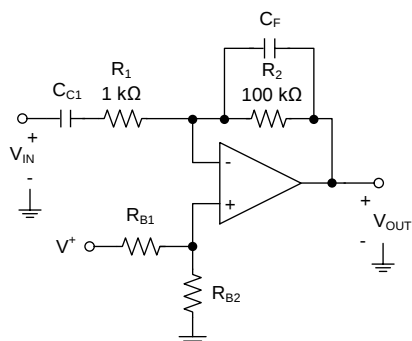
LMV55xは、2.7V $\sim$ 5.5Vの範囲の電源電圧で動作します。これらのアンプは広い温度範囲(-40 $^{\circ}$ C $\sim$ 125 $^{\circ}$ C)で動作するため、車載用アプリケーション、センサ・アプリケーションに加えて、携帯用計測機器アプリケーションにも最適です。LMV551は超小型の5ピンのSC70および5ピンのSOT-23パッケージで供給されます。LMV552は8ピンのVSSOPパッケージで供給されます。LMV554は14ピンのTSSOPで供給されます。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
LM551	SOT-23 (5)	2.90mm $\times$ 1.60mm
	SC70 (5)	2.00mm $\times$ 1.25mm
LMV552	VSSOP (8)	3.00mm $\times$ 3.00mm
LMV554	TSSOP (14)	5.00mm $\times$ 4.40mm

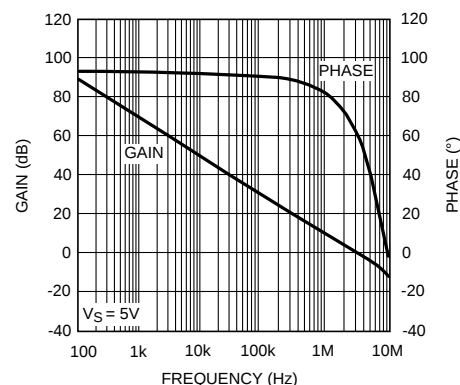
(1) 提供されているすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。

代表的なアプリケーションの回路図



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オープン・ループ・ゲインおよび位相と周波数との関係



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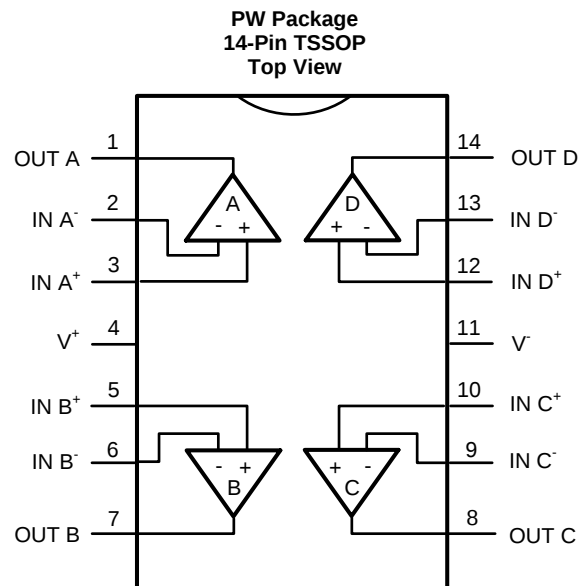
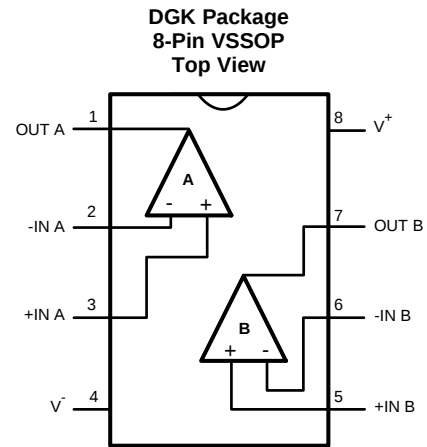
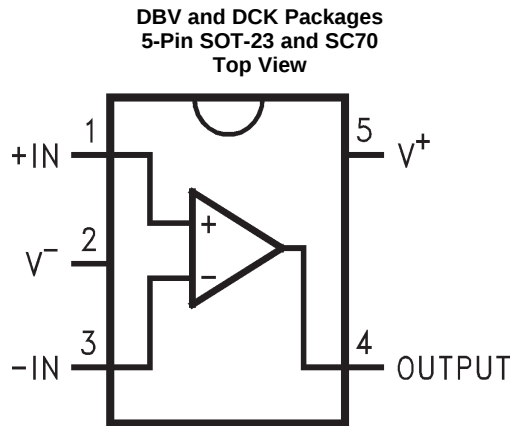
4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Revision G (February 2013) から Revision H に変更		Page
• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクション 追加		1
• Changed values in the <i>Thermal Information</i> table to align with JEDEC standards		5

Revision F (February 2013) から Revision G に変更		Page
• Changed layout of National Semiconductor Data Sheet to TI format.		18

5 Pin Configuration and Functions



LMV551, LMV552, LMV554

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Pin Functions: LMV551

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	LMV551		
	SOT-23, SC70		
+IN	1	I	Noninverting Input
-IN	3	I	Inverting Input
OUT	4	O	Output
V-	2	P	Negative Supply
V+	5	P	Positive Supply

(1) I = Input; O = Output; P = Power

Pin Functions: LMV552 and LMV554

PIN			TYPE ⁽¹⁾	DESCRIPTION
NAME	LMV552	LMV554		
	SOIC, VSSOP	SOIC, TSSOP		
+IN A	3	3	I	Noninverting input, channel A
+IN B	5	5	I	Noninverting input, channel B
+IN C	—	10	I	Noninverting input, channel C
+IN D	—	12	I	Noninverting input, channel D
-IN A	2	2	I	Inverting input, channel A
-IN B	6	6	I	Inverting input, channel B
-IN C	—	9	I	Inverting input, channel C
-IN D	—	13	I	Inverting input, channel D
OUT A	1	1	O	Output, channel A
OUT B	7	7	O	Output, channel B
OUT C	—	8	O	Output, channel C
OUT D	—	14	O	Output, channel D
V+	8	4	P	Positive (highest) power supply
V-	4	11	P	Negative (lowest) power supply

(1) I = Input; O = Output; P = Power

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

	MIN	MAX	UNIT
V _{IN} Differential (at V ⁺ = 5 V)		±2.5	V
Supply voltage (V ⁺ – V [–])		6	V
Voltage at input/output pins	V [–] –0.3	V ⁺ +0.3	V
Junction temperature, T _J ⁽³⁾		150	°C
Storage temperature, T _{stg}	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office / Distributors for availability and specifications.
- (3) The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} – T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human-body model (HBM) ⁽¹⁾	±2000	V
	Machine model (MM) ⁽²⁾	LMV551	
		LMV552 / LMV554	

- (1) Human Body Model, applicable std. MIL-STD-883, Method 3015.7.
- (2) Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC) Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

	MIN	NOM	MAX	UNIT
Temperature ⁽¹⁾	–40		125	°C
Supply voltage (V ⁺ – V [–])	2.7		5.5	V

- (1) The maximum power dissipation is a function of T_{J(MAX)}, θ_{JA}. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} – T_A) / θ_{JA}. All numbers apply for packages soldered directly onto a PC board.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		LMV551		LMV552	LMV554	UNIT
		DBV (SOT-23)	DCK (SC70)	DGK (VSSOP)	PW (TSSOP)	
		5 PINS	5 PINS	8 PINS	14 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	213.6	303.5	200.3	134.9	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	174.8	135.5	89.1	60.9	°C/W
R _{θJB}	Junction-to-board thermal resistance	72.6	81.1	120.9	77.3	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	56.6	8.4	21.7	11.5	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	72.2	80.4	119.4	76.7	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	n/a	n/a	n/a	n/a	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

LMV551, LMV552, LMV554

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6.5 Electrical Characteristics: 3 V

Unless otherwise specified, all limits are ensured for $T_A = 25^\circ\text{C}$, $V^+ = 3\text{ V}$, $V^- = 0\text{ V}$, $V_{CM} = V^+/2 = V_O$. ⁽¹⁾

PARAMETER		TEST CONDITIONS		MIN (2)	TYP ⁽²⁾	MAX ⁽²⁾	UNIT
V_{OS}	Input offset voltage	$T_A = 25^\circ\text{C}$			1	3	mV
		$T_A = -40^\circ\text{C}$ to 125°C				4.5	
TC V_{OS}	Input offset average drift	$T_A = -40^\circ\text{C}$ to 125°C			3.3		$\mu\text{V}/^\circ\text{C}$
I_B	Input bias current ⁽³⁾	$T_A = 25^\circ\text{C}$			20	38	nA
I_{OS}	Input offset current	$T_A = 25^\circ\text{C}$			1	20	nA
CMRR	Common mode rejection ratio	$0\text{ V} \leq V_{CM} \leq 2\text{ V}$	$T_A = 25^\circ\text{C}$	74	92		dB
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	72			
PSRR	Power supply rejection ratio	$3 \leq V^+ \leq 5\text{ V}$, $V_{CM} = 0.5\text{ V}$	LMV551 and LMV552	$T_A = 25^\circ\text{C}$	80	92	dB
				$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	78		
			LMV554	$T_A = 25^\circ\text{C}$	78	92	
				$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	76		
		$2.7 \leq V^+ \leq 5.5\text{ V}$, $V_{CM} = 0.5\text{ V}$	LMV551 and LMV552	$T_A = 25^\circ\text{C}$	80	92	
				$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	78		
			LMV554	$T_A = 25^\circ\text{C}$	78	92	
				$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	76		
CMVR	Input common-mode voltage	CMRR $\geq 68\text{ dB}$	$T_A = 25^\circ\text{C}$	0		2.1	V
		CMRR $\geq 60\text{ dB}$	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	0		2.1	
A_{VOL}	Large signal voltage gain	$0.4 \leq V_O \leq 2.6$, $R_L = 100\text{ k}\Omega$ to $V^+/2$	LMV551 and LMV552	$T_A = 25^\circ\text{C}$	81	90	dB
				$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	78		
			LMV554	$T_A = 25^\circ\text{C}$	79	90	
				$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	77		
		$0.4 \leq V_O \leq 2.6$, $R_L = 10\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$		71	80	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		68		
V_O	Output swing high	$R_L = 100\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$		40	48	mV from rail
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			58	
		$R_L = 10\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$		85	100	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			120	
	Output swing low	$R_L = 100\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$		50	65	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			77	
		$R_L = 10\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$		95	110	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			130	
I_{SC}	Output short circuit current	Sourcing ⁽⁴⁾			10		mA
		Sinking ⁽⁴⁾			25		
I_S	Supply current per amplifier	$T_A = 25^\circ\text{C}$			34	42	μA
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$				52	
SR	Slew rate	$A_V = +1$, 10% to 90% ⁽⁵⁾			1		V/ μs

- (1) Electrical Table values apply only for factor testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that $T_J = T_A$. No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where $T_J \neq T_A$.
- (2) Limits are 100% production tested at 25°C . Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Positive current corresponds to current flowing into the device.
- (4) The part is not short-circuit protected and is not recommended for operation with heavy resistive loads.
- (5) Slew rate is the average of the rising and falling slew rates.

Electrical Characteristics: 3 V (continued)

Unless otherwise specified, all limits are ensured for $T_A = 25^\circ\text{C}$, $V^+ = 3\text{ V}$, $V^- = 0\text{ V}$, $V_{CM} = V^+/2 = V_O$.⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN ⁽²⁾	TYP ⁽²⁾	MAX ⁽²⁾	UNIT
Φ_m	Phase margin	$R_L = 10\text{ k}\Omega$, $C_L = 20\text{ pF}$		75		°
GBW	Gain bandwidth product			3		MHz
e_n	Input-referred voltage noise	$f = 100\text{ kHz}$		70		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		70		
i_n	Input-referred current noise	$f = 100\text{ kHz}$		0.1		$\text{pA}/\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		0.15		
THD	Total harmonic distortion	$f = 1\text{ kHz}$, $A_V = 2$, $R_L = 2\text{ k}\Omega$		0.003%		

6.6 Electrical Characteristics: 5 V

Unless otherwise specified, all limits are ensured for $T_A = 25^\circ\text{C}$, $V^+ = 5\text{ V}$, $V^- = 0\text{ V}$, $V_{CM} = V^+/2 = V_O$.⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
V_{OS}	Input offset voltage	$T_A = 25^\circ\text{C}$		1	3	mV
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			4.5	
TC V_{OS}	Input offset average drift	$T_A = 25^\circ\text{C}$		3.3		$\mu\text{V}/^\circ\text{C}$
I_B	Input bias current ⁽⁴⁾	$T_A = 25^\circ\text{C}$		20	38	nA
I_{OS}	Input offset current			1	20	nA
CMRR	Common mode rejection ratio	$T_A = 25^\circ\text{C}$	76	93		nA
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	74			
PSRR	Power supply rejection ratio	$3\text{ V} \leq V^+ \leq 5\text{ V}$ to $V_{CM} = 0.5\text{ V}$	$T_A = 25^\circ\text{C}$	78	90	dB
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	75		
		$2.7\text{ V} \leq V^+ \leq 5.5\text{ V}$ to $V_{CM} = 0.5\text{ V}$	$T_A = 25^\circ\text{C}$	78	90	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	75		
CMVR	Input common-mode voltage	CMRR $\geq 68\text{ dB}$	$T_A = 25^\circ\text{C}$	0	4.1	V
		CMRR $\geq 60\text{ dB}$	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	0	4.1	
A_{VOL}	Large signal voltage gain	$0.4 \leq V_O \leq 4.6$, $R_L = 100\text{ k}\Omega$ to $V^+/2$		78	90	dB
				75		
		$0.4 \leq V_O \leq 4.6$, $R_L = 10\text{ k}\Omega$ to $V^+/2$		75	80	
				72		
V_O	Output swing high	$R_L = 100\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$	70	92	mV from rail
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		122	
		$R_L = 10\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$	125	155	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		210	
	Output swing low	$R_L = 100\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$	60	70	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		82	
		$R_L = 10\text{ k}\Omega$ to $V^+/2$	$T_A = 25^\circ\text{C}$	110	130	
			$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		155	
I_{SC}	Output short-circuit current	Sourcing ⁽⁵⁾		10		mA
		Sinking ⁽⁵⁾		25		
I_S	Supply current per amplifier	$T_A = 25^\circ\text{C}$		37	46	μA
		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			54	

(1) Electrical Table values apply only for factor testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that $T_J = T_A$. No guarantee of parametric performance is indicated in the electrical tables under conditions of internal self-heating where $T_J \neq T_A$.

(2) Limits are 100% production tested at 25°C . Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and also depend on the application and configuration. The typical values are not tested and are not ensured on shipped production material.

(4) Positive current corresponds to current flowing into the device.

(5) The part is not short-circuit protected and is not recommended for operation with heavy resistive loads.

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Electrical Characteristics: 5 V (continued)

 Unless otherwise specified, all limits are ensured for $T_A = 25^\circ\text{C}$, $V^+ = 5\text{ V}$, $V^- = 0\text{ V}$, $V_{CM} = V^+/2 = V_O$.⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
SR	Slew rate	$A_V = +1$, $V_O = 1\text{ V}_{PP}$ 10% to 90% ⁽⁶⁾		1		V/ μs
Φ_m	Phase margin	$R_L = 10\text{ k}\Omega$, $C_L = 20\text{ pF}$		75		°
GBW	Gain bandwidth product			3		MHz
e_n	Input-referred voltage noise	$f = 100\text{ kHz}$		70		nV/ $\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		70		
I_n	Input-referred current noise	$f = 100\text{ kHz}$		0.1		pA/ $\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		0.15		
THD	Total harmonic distortion	$f = 1\text{ kHz}$, $A_V = 2$, $R_L = 2\text{ k}\Omega$		0.003%		

(6) Slew rate is the average of the rising and falling slew rates.

6.7 Typical Characteristics

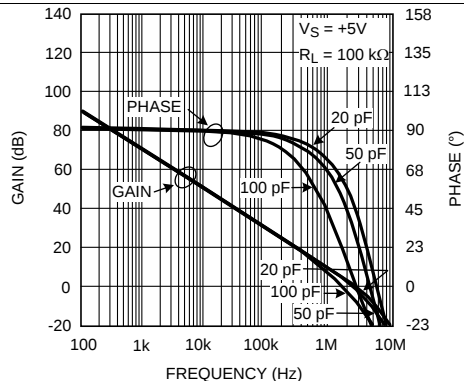


Figure 1. Open-Loop Gain and Phase With Capacitive Load

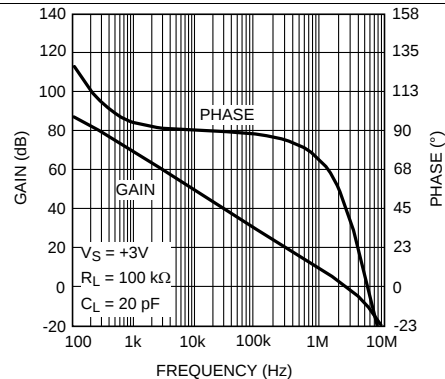


Figure 2. Open-Loop Gain and Phase With Resistive Load

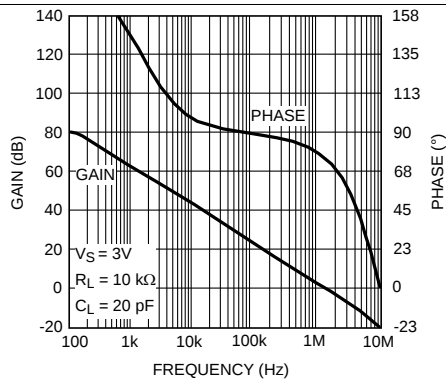


Figure 3. Open-Loop Gain and Phase With Resistive Load

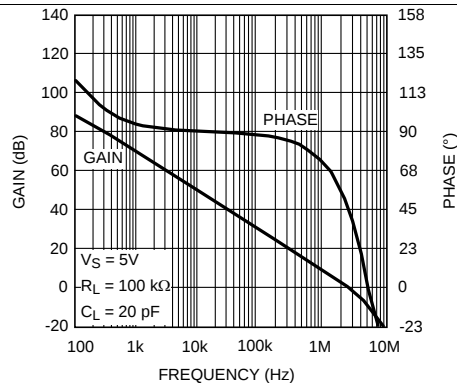


Figure 4. Open-Loop Gain and Phase With Resistive Load

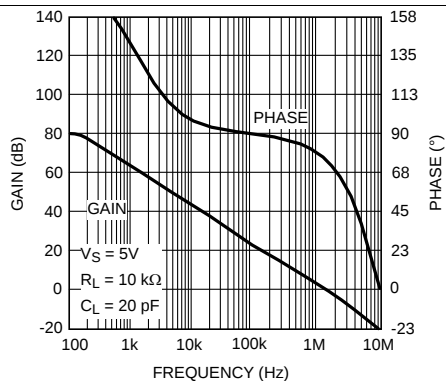


Figure 5. Open-Loop Gain and Phase With Resistive Load

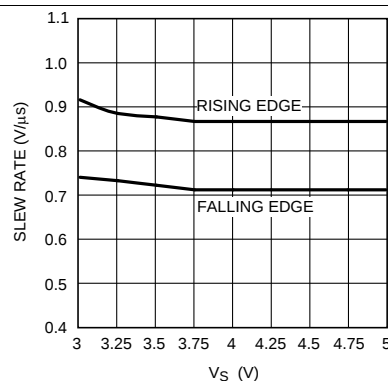
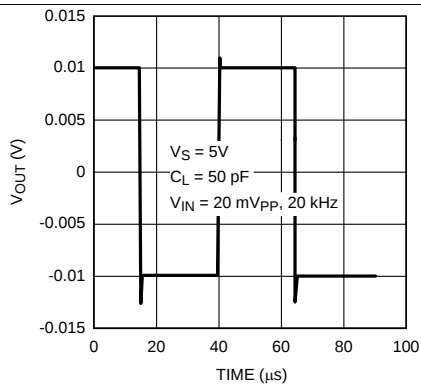
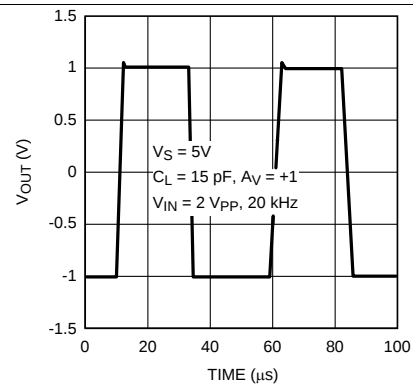
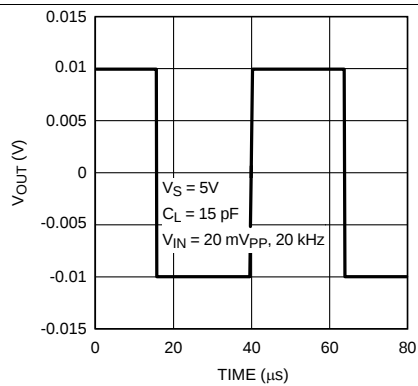
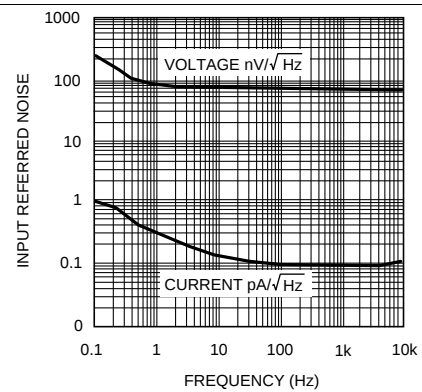
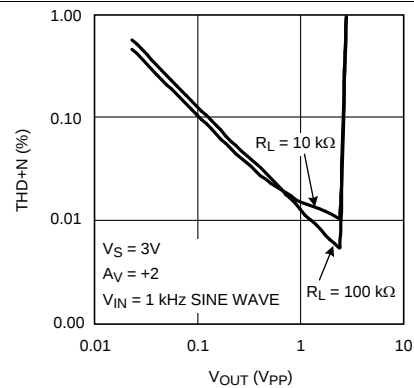
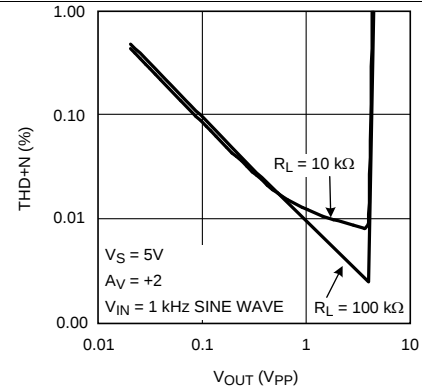


Figure 6. Slew Rate vs Supply voltage

Typical Characteristics (continued)

Figure 7. Small-Signal Transient Response

Figure 8. Large-Signal Transient Response

Figure 9. Small-Signal Transient Response

Figure 10. Input Referred Noise vs Frequency

Figure 11. THD+N vs Amplitude at 3 V

Figure 12. THD+N vs Amplitude at 5 V

Typical Characteristics (continued)

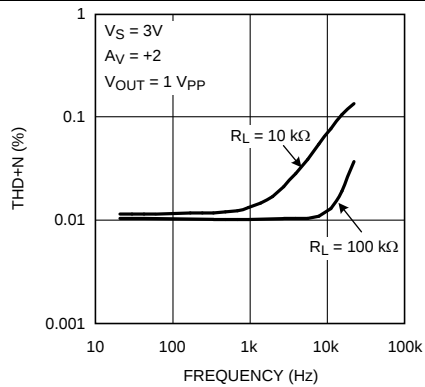


Figure 13. THD+N vs Amplitude

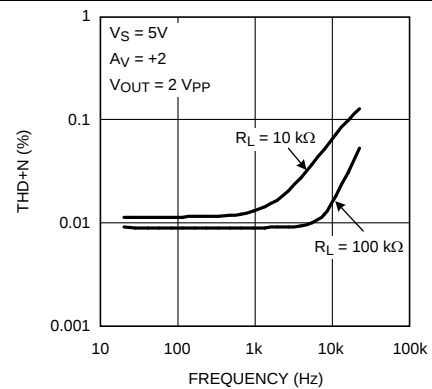


Figure 14. THD+N vs Amplitude

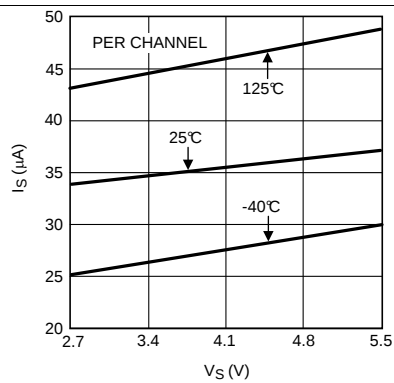


Figure 15. Supply Current vs Supply Voltage

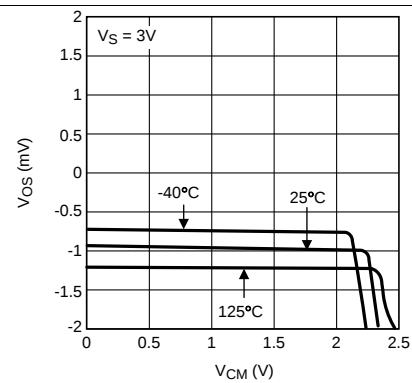


Figure 16. V_{OS} vs V_{CM}

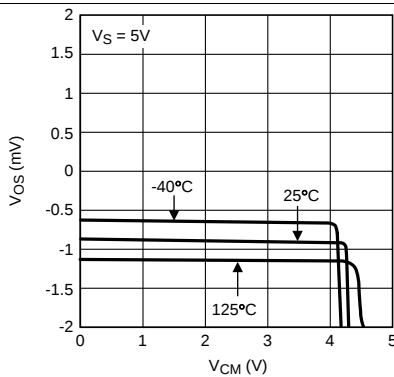


Figure 17. V_{OS} vs V_{CM}

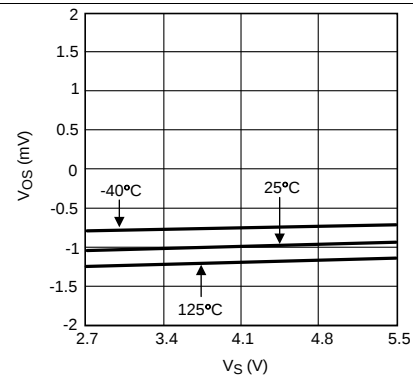
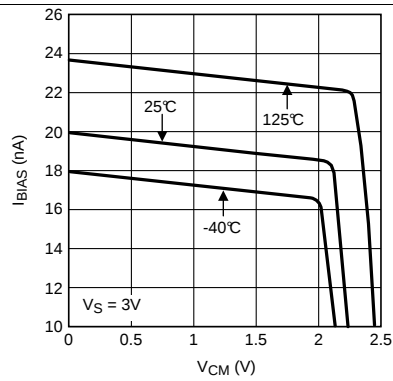
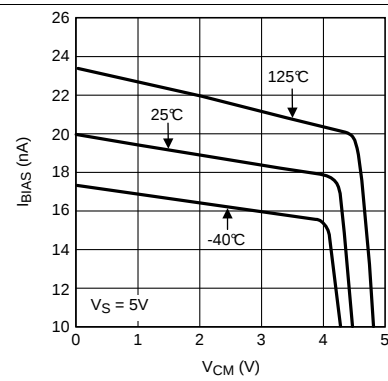
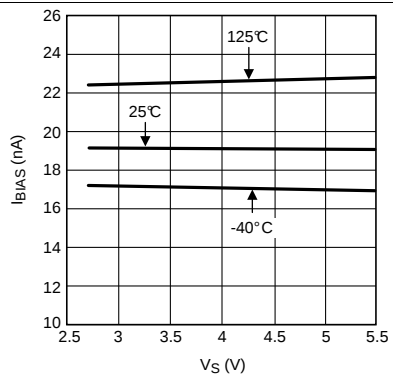
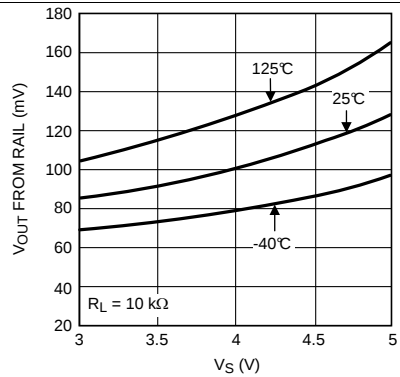
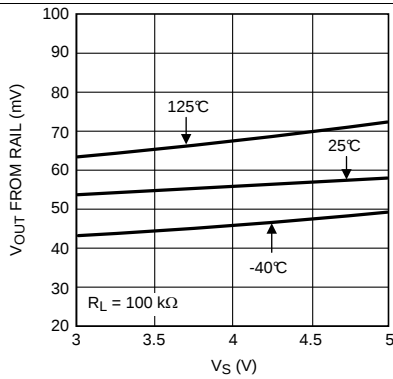
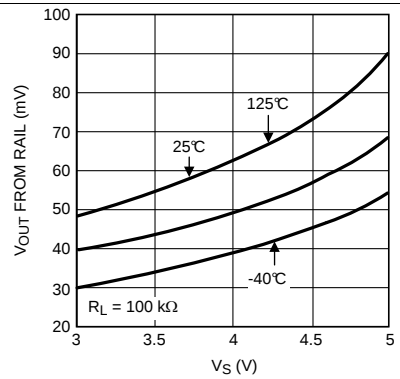


Figure 18. V_{OS} vs Supply Voltage

Typical Characteristics (continued)

Figure 19. I_{BIAS} vs V_{CM}

Figure 20. I_{BIAS} vs V_{CM}

Figure 21. I_{BIAS} vs Supply Voltage

Figure 22. Positive Output Swing vs Supply Voltage

Figure 23. Negative Output Swing vs Supply Voltage

Figure 24. Positive Output Swing vs Supply Voltage

Typical Characteristics (continued)

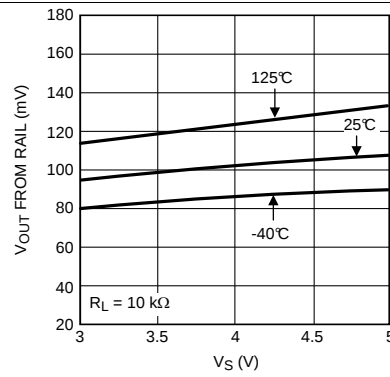


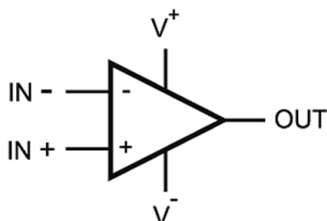
Figure 25. Negative Output Swing vs Supply Voltage

7 Detailed Description

7.1 Overview

The LMV55x are high performance, low power operational amplifiers implemented with TI's advanced VIP50 process. They feature 3 MHz of bandwidth while consuming only 37 μ A of current per amplifier, which is an exceptional bandwidth to power ratio in this op amp class. These amplifiers are unity gain stable and provide an excellent solution for low power applications requiring a wide bandwidth.

7.2 Functional Block Diagram



(Each Amplifier)

7.3 Feature Description

The differential inputs of the amplifier consist of a noninverting input (+IN) and an inverting input (–IN). The amplifier amplifies only the difference in voltage between the two inputs, which is called the differential input voltage. The output voltage of the op-amp V_{OUT} is given by [Equation 1](#):

$$V_{OUT} = A_{OL} (IN^+ - IN^-)$$

where

- A_{OL} is the open-loop gain of the amplifier, typically around 100 dB (100,000x, or 10 μ V per volt). (1)

7.3.1 Low Voltage and Low Power Operation

The LMV55x have performance ensured at supply voltages of 3 V and 5 V and are ensured to be operational at all supply voltages from 2.7 V to 5.5 V. For this supply voltage range, the LMV55x draw the extremely low supply current of less than 37 μ A per amp.

7.3.2 Wide Bandwidth

The bandwidth to power ratio of 3 MHz to 37 μ A per amplifier is one of the best bandwidth to power ratios ever achieved. This makes these devices ideal for low power signal processing applications such as portable media players and instrumentation.

7.3.3 Low Input Referred Noise

The LMV55x provide a flatband input referred voltage noise density of 70 $\text{nV}/\sqrt{\text{Hz}}$, which is significantly better than the noise performance expected from an ultra low power op amp. They also feature the exceptionally low 1/f noise corner frequency of 4 Hz. This noise specification makes the LMV55x ideal for low power applications such as PDAs and portable sensors.

7.3.4 Ground Sensing and Rail-to-Rail Output

The LMV55x each have a rail-to-rail output stage, which provides the maximum possible output dynamic range. This is especially important for applications requiring a large output swing. The input common mode range includes the negative supply rail which allows direct sensing at ground in a single supply operation.

Feature Description (continued)

7.3.5 Small Size

The small footprints of the LMV55x packages save space on printed circuit boards, and enable the design of smaller and more compact electronic products. Long traces between the signal source and the op amp make the signal path susceptible to noise. By using a physically smaller package, the amplifiers can be placed closer to the signal source, reducing noise pickup and enhancing signal integrity.

7.4 Device Functional Modes

7.4.1 Stability Of Op Amp Circuits

7.4.1.1 Stability and Capacitive Loading

As seen in the Phase Margin vs Capacitive Load graph, the phase margin reduces significantly for C_L greater than 100 pF. This is because the op amp is designed to provide the maximum bandwidth possible for a low supply current. Stabilizing them for higher capacitive loads would have required either a drastic increase in supply current, or a large internal compensation capacitance, which would have reduced the bandwidth of the op amp. Hence, if the LMV55x are to be used for driving higher capacitive loads, they must be externally compensated.

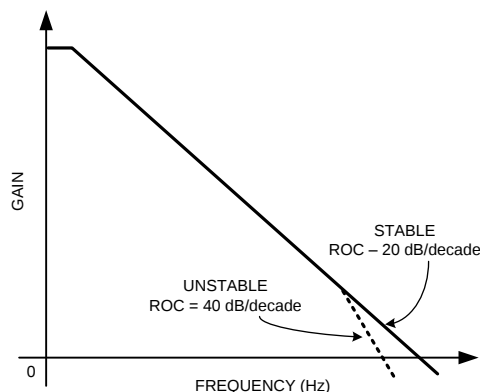


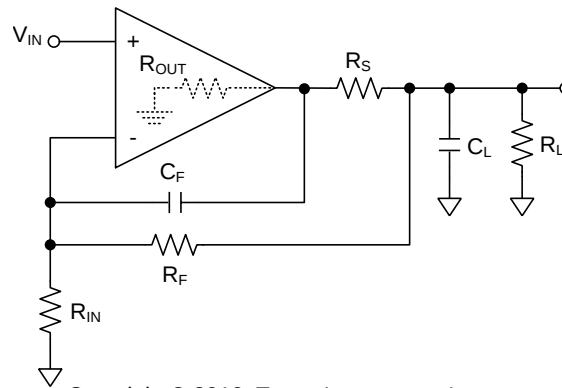
Figure 26. Gain vs Frequency for an Op Amp

An op amp, ideally, has a dominant pole close to DC, which causes its gain to decay at the rate of 20 dB/decade with respect to frequency. If this rate of decay, also known as the rate of closure (ROC), remains the same until the op amp's unity gain bandwidth, the op amp is stable. If, however, a large capacitance is added to the output of the op amp, it combines with the output impedance of the op amp to create another pole in its frequency response before its unity gain frequency (Figure 26). This increases the ROC to 40 dB/decade and causes instability.

In such a case a number of techniques can be used to restore stability to the circuit. The idea behind all these schemes is to modify the frequency response such that it can be restored to an ROC of 20 dB/decade, which ensures stability.

7.4.1.1.1 In the Loop Compensation

Figure 27 illustrates a compensation technique, known as 'in the loop' compensation, that employs an RC feedback circuit within the feedback loop to stabilize a non-inverting amplifier configuration. A small series resistance, R_S , is used to isolate the amplifier output from the load capacitance, C_L , and a small capacitance, C_F , is inserted across the feedback resistor to bypass C_L at higher frequencies.

Device Functional Modes (continued)


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Figure 27. In the Loop Compensation

The values for R_S and C_F are decided by ensuring that the zero attributed to C_F lies at the same frequency as the pole attributed to C_L . This ensures that the effect of the second pole on the transfer function is compensated for by the presence of the zero, and that the ROC is maintained at 20 dB/decade. For the circuit shown in [Figure 27](#) the values of R_S and C_F are given by [Equation 2](#). Values of R_S and C_F required for maintaining stability for different values of C_L , as well as the phase margins obtained, are shown in [Table 1](#). R_F , R_{IN} , and R_L are to be 10 k Ω , while R_{OUT} is 340 Ω .

$$R_S = \frac{R_{OUT}R_{IN}}{R_F}$$

$$C_F = \left(1 + \frac{1}{A_{CL}}\right) \left(\frac{R_F + 2R_{IN}}{R_F^2}\right) C_L R_{OUT} \quad (2)$$

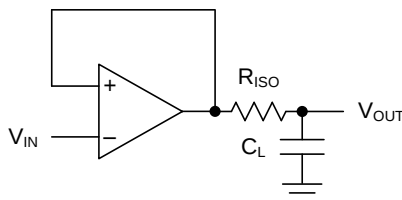
Table 1. Phase Margins

C_L (pF)	R_S (Ω)	C_F (pF)	PHASE MARGIN ($^\circ$)
50	340	8	47
100	340	15	42
150	340	22	40

Although this methodology provides circuit stability for any load capacitance, it does so at the price of bandwidth. The closed loop bandwidth of the circuit is now limited by R_F and C_F .

7.4.1.1.2 Compensation by External Resistor

In some applications it is essential to drive a capacitive load without sacrificing bandwidth. In such a case, in the loop compensation is not viable. A simpler scheme for compensation is shown in [Figure 28](#). A resistor, R_{ISO} , is placed in series between the load capacitance and the output. This introduces a zero in the circuit transfer function, which counteracts the effect of the pole formed by the load capacitance and ensures stability. The value of R_{ISO} to be used should be decided depending on the size of C_L and the level of performance desired. Values ranging from 5 Ω to 50 Ω are usually sufficient to ensure stability. A larger value of R_{ISO} results in a system with less ringing and overshoot, but also limits the output swing and the short-circuit current of the circuit.



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Figure 28. Compensation by Isolation Resistor

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LMV55x have an operating supply voltage range from 2.7 V to 5.5 V. These amplifiers can operate over a wide temperature range (-40°C to 125°C), making them a great choice for automotive applications, sensor applications as well as portable instrumentation applications.

With a wide unity gain bandwidth of 3 MHz, low input referred noise density and an excellent BW to supply current ratio, the LMV55x are well suited for low-power filtering applications. Active filter topologies, such as the Sallen-Key low pass filter shown in Figure 29, are very versatile, and can be used to design a wide variety of filters (Chebyshev, Butterworth or Bessel). For best results, the amplifier must have a bandwidth that is eight to ten times the filter frequency bandwidth. Failure to follow this guideline can result in phase shift of the amplifier and premature roll-off. The Sallen-Key topology, in particular, can be used to attain a wide range of Q, by using positive feedback to reject the undesired frequency range.

8.2 Typical Application

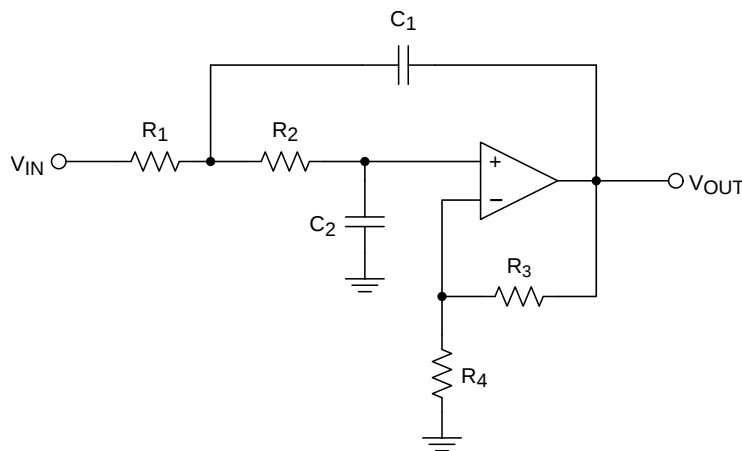


Figure 29. Two Pole Sallen-Key Low Pass Filter

8.2.1 Design Requirements

As a design example:

Require: $A_{LP} = 10$, less than 1dB passband ripple, and a cutoff frequency of 1kHz.

8.2.2 Detailed Design Procedure

There are many resources discussing the Sallen-Key lowpass filter topology.

Texas Instruments has made filter design easy by creating on-line and stand alone design tools, such as Webench Filter Designer and Filter Pro Desktop.

For this design, the stand-alone Filter Pro Desktop is used.

For the design, the following parameters are entered into the Filterpro software:

1. Filter Type = Lowpass
2. Gain = 10 V/V (20dB)
3. Passband Frequency = 1 kHz

Typical Application (continued)

4. Allowable Ripple = 1 dB
5. Filter Order = Checked and set to 2
6. Response Type = Butterworth
7. Filter Topology = Sallen-Key
8. Component Tolerance - Resistor = E96 1%
9. Component Tolerance - Capacitor = E6 20%

After entering these values, FilterPro returns the following recommended values:

1. R1 = 44.2 kΩ
2. R2 = 38.3 kΩ
3. R3 = 2.49 kΩ
4. R4 = 22.6 kΩ
5. C1 = 10 nF
6. C2 = 1.5 nF

The LMV55x is targeted for low power operation. The above resistor values are assumed for a *standard* power application. To save power, both quiescent and dynamic, the values of the resistors can be increased.

The largest consumer of power is the gain setting feedback resistors R3 and R4, as these are DC coupled and represent a constant DC load to the amplifier. If the output is biased at 2.5 V, then $2.5 \text{ V} / (22.6 \text{ k} + 2.49 \text{ k}) = 99.6 \text{ } \mu\text{A}$ is flowing through the feedback network. This is significantly more than the 37uA quiescent current of the amplifier alone! Increasing the size of the feedback resistors by a decade from 22.6k to 226k, the current in the feedback network can be reduced down to 9.9uA.

Increasing the resistor values requires a proportional decrease in the values of the capacitors. If a resistor value is increased 10×, then the corresponding capacitor value must be decreased 10×. However, note that increasing the resistor values increases the contributed noise, and decreasing the capacitors to small values increases the sensitivity to stray capacitance.

There is a decision to be made about also scaling the filter components (R1, R2, C1 & C2). R1 and R2 are AC coupled to the output, so the only DC current flowing through these resistors is the input bias current of the LMV55x (typically 20 nA). However, large AC currents can flow through C2 and C1 during large signal swings. Scaling the filter components also reduces the peak AC signal currents. If the AC signals are expected to large (several Vpp) and frequent, then scaling the filter values may be beneficial to overall power consumption. If the expected AC signals are small, it may not be worth the noise tradeoff to scale these values.

Because the LMV55x has a bipolar input, to maintain DC accuracy, the equivalent resistance seen by each amplifier input should be equal to cancel the bias current effects.

To maintain DC accuracy through bias current cancelling, the following relationship should be maintained:

$$(R1 + R2) = (R3 \parallel R4) \quad (3)$$

Fortunately, the filter Pro software makes changing and recalculating the values easy. By changing the value of any of the filter components (R1, R2, C1 & C2) in the schematic tab, the program automatically recalculates and scale these components. Conversely, changing the gain feedback components (R3 or R4) also causes the other feedback resistor to scale. However, Filter Pro does NOT maintain the relationship between the feedback and filter elements as described in [Equation 3](#) above. The feedback resistor values can be 'seeded' and scaled appropriately, as long as the original feedback resistor ratio is maintained.

Typical Application (continued)

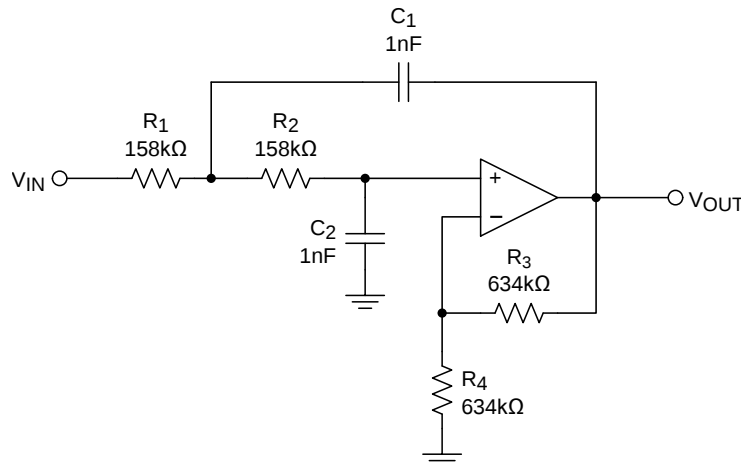


Figure 30. 1kHz Sallen-Key Low Pass Filter with Values

8.2.3 Application Curve

Figure 31 shows the simulated results of the example 1-KHz Sallen-Key Low Pass Filter.

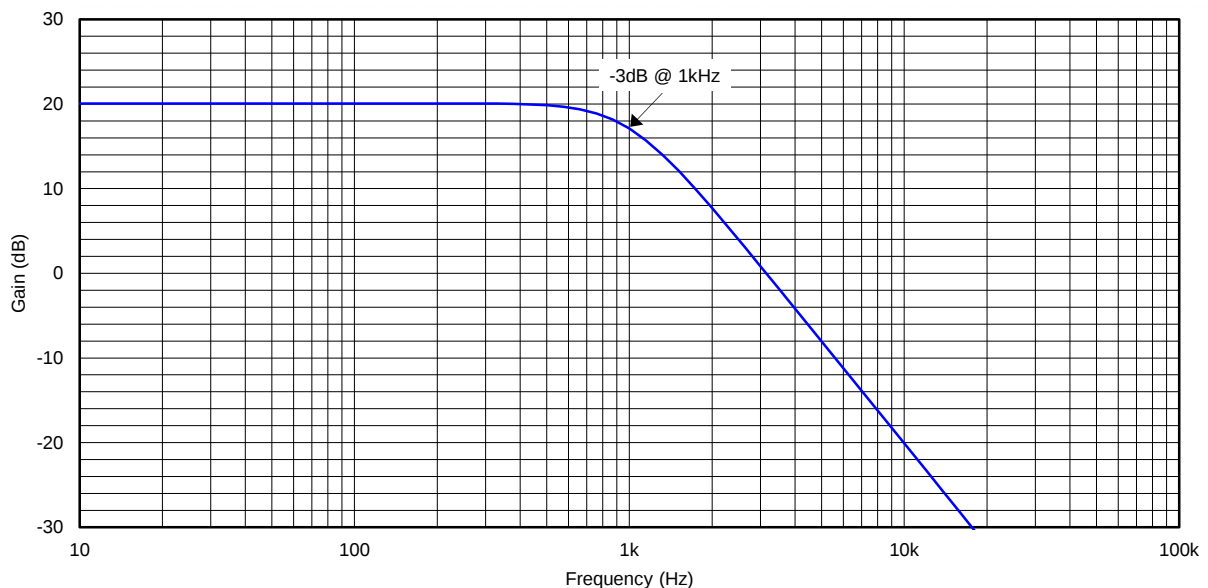


Figure 31. 1KHz, 2-Pole Sallen-Key Low Pass Filter Results

8.3 Do's and Don'ts

Do properly bypass the power supplies.

Do add series resistance to the output when driving capacitive loads, particularly cables, Muxes and ADC inputs.

Do add series current limiting resistors and external Schottky clamp diodes if input voltage is expected to exceed the supplies. Limit the current to 1 mA or less (1 kΩ per volt).

9 Power Supply Recommendations

For proper operation, the power supplies must be properly decoupled. For decoupling the supply lines, TI recommends that 10-nF capacitors be placed as close as possible to the op amp power supply pins. For single-supply, place a capacitor between V^+ and V^- supply leads. For dual supplies, place one capacitor between V^+ and ground, and one capacitor between V^- and ground.

10 Layout

10.1 Layout Guidelines

The V^+ pin should be bypassed to ground with a low-ESR capacitor.

The optimum placement is closest to the V^+ and ground pins.

Take care to minimize the loop area formed by the bypass capacitor connection between V^+ and ground.

The ground pin should be connected to the PCB ground plane at the pin of the device.

The feedback components should be placed as close to the device as possible minimizing strays.

10.2 Layout Example

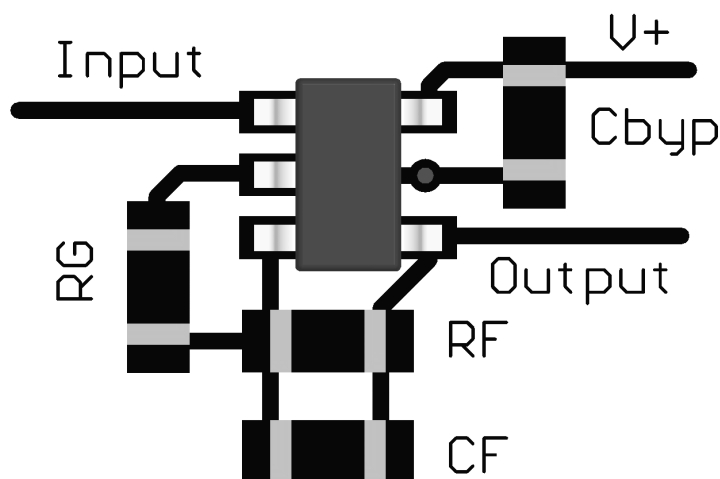


Figure 32. SOT-23 Layout Example

11 デバイスおよびドキュメントのサポート

11.1 デバイス・サポート

11.1.1 開発サポート

[LMV551 PSPICEモデル\(SNOM060\)](#)

[LMV552 PSPICEモデル\(SNOM061\)](#)

[LMV554 PSPICEモデル\(SNOM062\)](#)

[TINA-TI SPICEベースのアナログ・シミュレーション・プログラム](#)

[DIP アダプタ評価モジュール](#)

[TIユニバーサル・オペアンプ評価モジュール](#)

[TI Filterproソフトウェア](#)

11.2 ドキュメントのサポート

11.2.1 関連資料

追加アプリケーションについては、[『AN-31 オペアンプ回路コレクション』\(SNLA140\)](#)を参照してください。

11.3 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

表 2. 関連リンク

製品	プロダクト・フォルダ	サンプルとご購入	技術資料	ツールとソフトウェア	サポートとコミュニティ
LMV551	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
LMV552	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
LMV554	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

11.4 ドキュメントの更新通知を受け取る方法

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11.5 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

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11.8 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。これらの情報は、指定のデバイスに対して提供されている最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMV551MF/NOPB	Active	Production	SOT-23 (DBV) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AF3A
LMV551MF/NOPB.A	Active	Production	SOT-23 (DBV) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AF3A
LMV551MFX/NOPB	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AF3A
LMV551MFX/NOPB.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AF3A
LMV551MFX/NOPB.B	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	-	SN	Level-1-260C-UNLIM	-40 to 125	AF3A
LMV551MG/NOPB	Active	Production	SC70 (DCK) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A94
LMV551MG/NOPB.A	Active	Production	SC70 (DCK) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A94
LMV551MG/NOPB.B	Active	Production	SC70 (DCK) 5	1000 SMALL T&R	-	SN	Level-1-260C-UNLIM	-40 to 125	A94
LMV551MGX/NOPB	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A94
LMV551MGX/NOPB.A	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A94
LMV551MGX/NOPB.B	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	-	SN	Level-1-260C-UNLIM	-40 to 125	A94
LMV552MM/NOPB	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AH3A
LMV552MM/NOPB.A	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AH3A
LMV552MM/NOPB.B	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	-	SN	Level-1-260C-UNLIM	-40 to 125	AH3A
LMV552MMX/NOPB	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AH3A
LMV552MMX/NOPB.A	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AH3A
LMV552MMX/NOPB.B	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	-	SN	Level-1-260C-UNLIM	-40 to 125	AH3A
LMV554MT/NOPB	Active	Production	TSSOP (PW) 14	94 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV55 4MT
LMV554MT/NOPB.A	Active	Production	TSSOP (PW) 14	94 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV55 4MT
LMV554MTX/NOPB	Active	Production	TSSOP (PW) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV55 4MT
LMV554MTX/NOPB.A	Active	Production	TSSOP (PW) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV55 4MT

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF LMV551 :

- Automotive : [LMV551-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV551MF/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV551MFX/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV551MG/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LMV551MGX/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LMV552MM/NOPB	VSSOP	DGK	8	1000	177.8	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LMV552MMX/NOPB	VSSOP	DGK	8	3500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LMV554MTX/NOPB	TSSOP	PW	14	2500	330.0	12.4	6.95	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV551MF/NOPB	SOT-23	DBV	5	1000	208.0	191.0	35.0
LMV551MFX/NOPB	SOT-23	DBV	5	3000	208.0	191.0	35.0
LMV551MG/NOPB	SC70	DCK	5	1000	208.0	191.0	35.0
LMV551MGX/NOPB	SC70	DCK	5	3000	208.0	191.0	35.0
LMV552MM/NOPB	VSSOP	DGK	8	1000	208.0	191.0	35.0
LMV552MMX/NOPB	VSSOP	DGK	8	3500	367.0	367.0	35.0
LMV554MTX/NOPB	TSSOP	PW	14	2500	367.0	367.0	35.0

TUBE

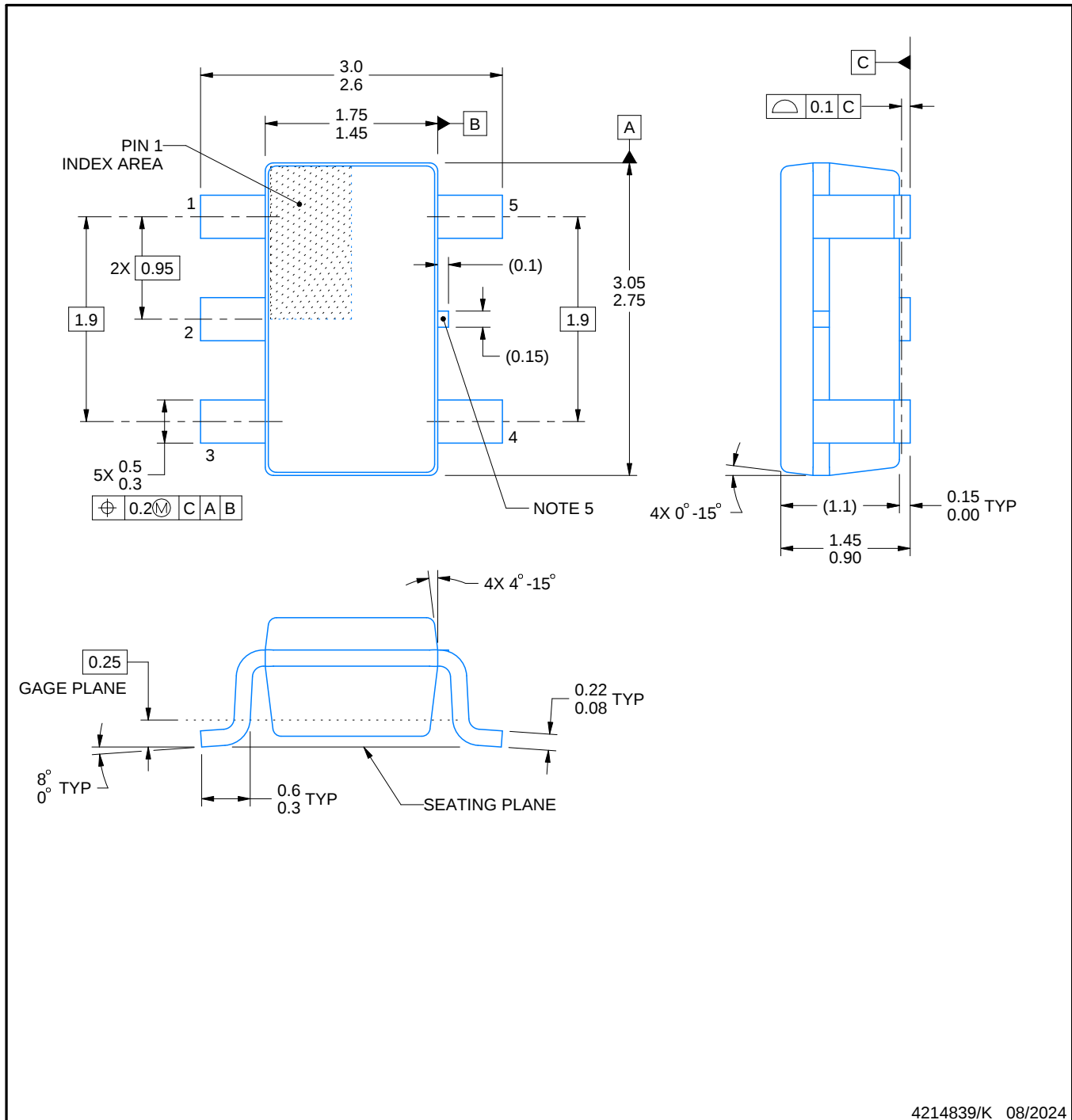


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LMV554MT/NOPB	PW	TSSOP	14	94	495	8	2514.6	4.06
LMV554MT/NOPB.A	PW	TSSOP	14	94	495	8	2514.6	4.06

DBV0005A**PACKAGE OUTLINE****SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



4214839/K 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

EXAMPLE BOARD LAYOUT

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



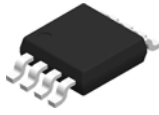
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DGK0008A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

NOTES:

PowerPAD is a trademark of Texas Instruments.

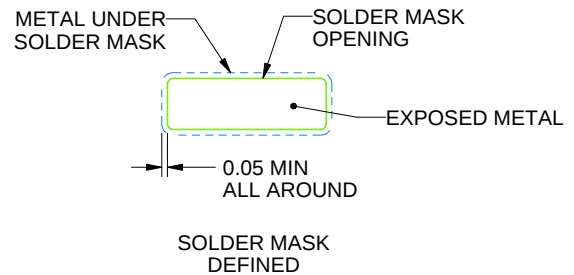
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.



SOT - 1.1 max height

Technical drawing of a mechanical part showing three views: front, side, and top.

Front View Dimensions:

- Overall width: 2.4 (1.8)
- Overall height: 2.15 (1.85)
- Horizontal hole positions: 1.4 (1.1)
- Vertical hole positions: 1.3 (1.3)
- Hole diameters: (0.15), (0.1)
- Feature control frame: $\oplus$ 0.1 C A B
- Note 5: 5X 0.33 0.15
- Note 4: (0.15), (0.1)
- Feature control frame: C A B

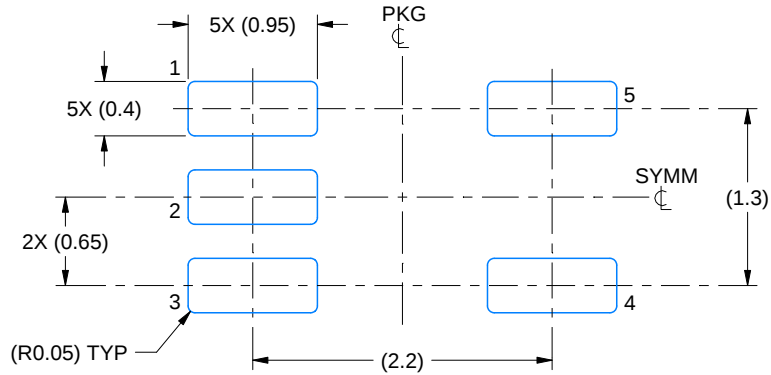
Side View Dimensions:

- Maximum width: 1.1 MAX
- Chamfer: 4X 0°-12°
- Dimension: (0.9)
- Dimension: 0.1 0.0 TYP

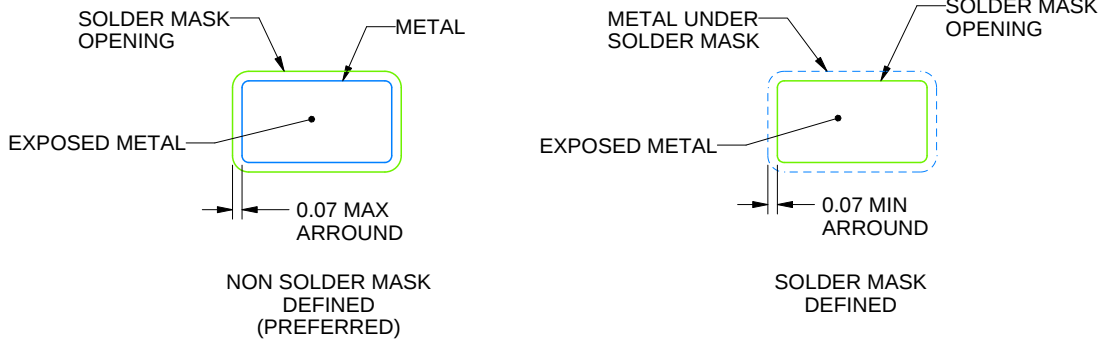
Top View Dimensions:

- GAGE PLANE
- SEATING PLANE
- Chamfer: 4X 4°-15°
- Dimension: 0.15
- Dimension: 0.22 0.08 TYP
- Dimension: 0.46 0.26 TYP
- Angle: 8° 0° TYP

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4214834/G 11/2024

NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 THICK STENCIL
 SCALE:18X

4214834/G 11/2024

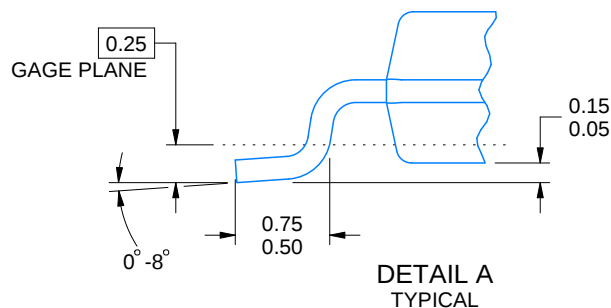
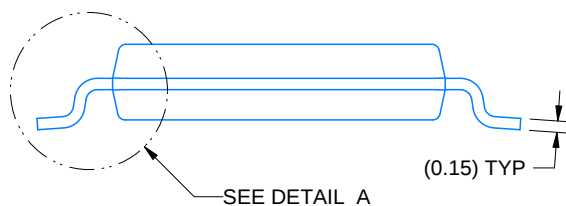
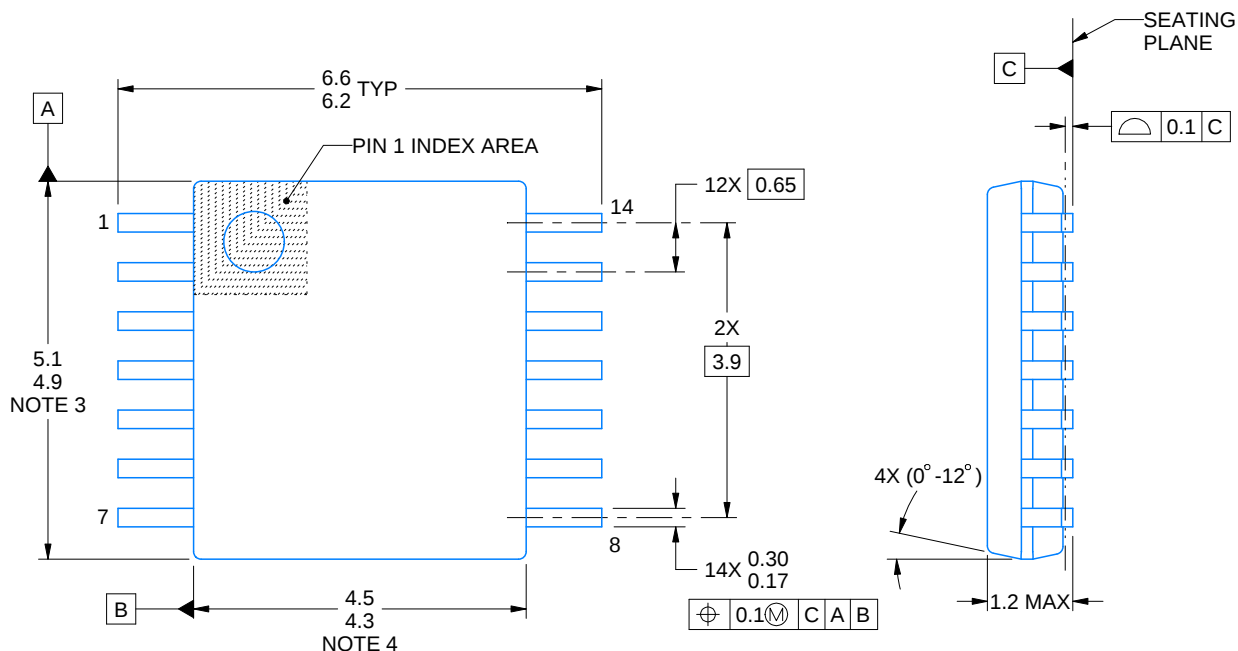
NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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